Zytel® HTN92G35DH2 BK083

PA6T/66-GF35 Celanese

Product Texts

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTN92G35DH2 BK083 is a 35% glass reinforced high performance polyamide resin using our SHIELD Technology, with high flow and excellent retention of properties after aging at elevated temperatures in air. It is also a PPA resin.

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
[C] Melt volume-flow rate, MVR	**60 / ***	cm³/10min	ISO 1133
Temperature	**325 / ***	°C	-
Load	**2.16 / ***	kg	-
[C] Molding shrinkage, parallel	**0.2 / ***	%	ISO 294-4, 2577
[C] Molding shrinkage, normal	**0.9 / ***	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
[C] Tensile Modulus	**12000 / 10000**	MPa	ISO 527
[C] Stress at break	**200 / 160**	MPa	ISO 527
[C] Strain at break	**2.4 / 2.6**	%	ISO 527
[C] Tensile creep modulus, 1h	*** / 10000**	MPa	ISO 899-1
[C] Tensile creep modulus, 1000h	*** / 8500**	MPa	ISO 899-1
[C] Charpy impact strength, +23°C	**55 / 50**	kJ/m²	ISO 179/1eU
[C] Charpy impact strength, -30°C	**50 / 45**	kJ/m²	ISO 179/1eU
[C] Charpy notched impact strength, +23°C	**10 / 10**	kJ/m²	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
[C] Glass transition temperature, 10°C/min	**75 / ***	°C	ISO 11357-1/-2
[C] Temp. of deflection under load, 1.80 MPa	**283 / ***	°C	ISO 75-1/-2
[C] Coeff. of linear therm. expansion, parallel	**30 / ***	E-6/K	ISO 11359-1/-2
[C] Coeff. of linear therm. expansion, normal	**80 / ***	E-6/K	ISO 11359-1/-2

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
[C] Volume resistivity	**>1E13 / 1E13**	Ohm*m	IEC 62631-3-1
[C] Surface resistivity	*** / 1E13**	Ohm	IEC 62631-3-2
[C] Electric strength	**32 / -**	kV/mm	IEC 60243-1
[C] Comparative tracking index	**600 / -**	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
[C] Density	**1440 / -**	kg/m³	ISO 1183

[C]: CAMPUS

Material specific properties	dry / cond	Unit	Test Standard
ISO Data			
[C] Viscosity number	**115 / ***	cm³/g	ISO 307, 1157, 1628

[C]: CAMPUS

Characteristics

Processing
Injection Molding

Delivery form
Pellets

Additives
Release agent

Special Characteristics
Heat stabilized or stable to heat

Chemical Resistance
General Chemical Resistance

Applications
Automotive, Electrical and Electronical

Regional Availability
Europe

Other text information

Injection molding
During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.